Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
SI	0	jp-43006302-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 09:44
S2	0	jp-4306302-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 09:44
S3	1	jp-04306302-\$.did.	US-PGPUB; USPAT;	OR	ON	2005/08/17 09:45
			USOCR; EPO; JPO; DERWENT ; IBM_TDB		0	
S4	0	jp-043006302-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 09:45
S5	- 2 8	suzuki-munehiko.in. suzuki-munehiko-\$.in.	US-PGPUB; USPAT;	OR	ON	2005/08/17 09:55
			USOCR; EPO; JPO;		- ō	
		* 0 · v	DERWENT ; IBM_TDB	. ,		•
S6	217	kawamata-takeshi.in. kawamata-takeshi-\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 09:51
S7	. 223	hosokawa-etsuo.in. hosokawa-etsuo-4.in.	US-PGPUB; USPAT;	OR	ON	2005/08/17 09:51
			USOCR;		***	
	*		EPO; JPO; DERWENT ; IBM_TDB			
S8	1171	munehiko	EPO; JPO; DERWENT	OR	ON	2005/08/17 09:52
S9	0	munehiko and trimellitimides	EPO; JPO; DERWENT	OR	ON	2005/08/17 09:53
S10	0	munehiko and trimellitimide	EPO; JPO; DERWENT	OR	ON	2005/08/17 09:53
S11	56	trimellitimide	EPO; JPO; DERWENT	OR	ON	2005/08/17 10:15
S12	0	(S6 S7 S5) and trimellitimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 09:58
S13	518364	epox\$5 polyepox\$5 diepox\$5 ((glycidyl diglycidyl polyglycidyl) adj ether) diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:58

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S14	11	(S6 S7 S5) and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 09:58
S15	130	trimellitimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:16
S16	518364	epox\$5 polyepox\$5 diepox\$5 ((glycidyl diglycidyl polyglycidyl) adj ether) diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:16
S17	• 26	S15 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:24
S18	11960	diaminodiphenylmethane (diamino adj diphenylmethane) (diaminodiphenyl adj methane) (diamino adj diphenyl adj methane) .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:20
S19	0	diaminodiphenylmethanetrimellitimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:20
S20	2	S18 with S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:20
S21	290753	"pcb" "pwb" (printed adj2 (circuit wiring) adj2 board)	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR .	ON	2005/08/17 14:08
	•		DERWENT ; IBM_TDB	·		
S22	1	S17 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:28
S23	38268	S21 and S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:29
S24	46795	heat adj2 (stable stability)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:03

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S25	315	S23 and S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:29
S26	11273	halogenfree (free near2 halogen) "halogen-free"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:44
S27	14	S25 and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:32
S28	315	S21 and S13 and S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 10:33
S29	1080940	silica (silicon adj2 (oxide dioxide)) (titanium adj2 (oxide dioxide)) alumina ((aluminum magnesium) adj2 hydroxide) (calcium adj2 carbonate)	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:30
S30	201	S28 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:38
S31	1672085	(aluminum adj2 (nitride oxide)) (boron adj2 nitride) silver aluminum (zinc adj2 oxide) nanotube (nano adj tube) "nano-tube"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:31
S32	175	S30 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON = .	2005/08/17 10:41
S33	94	S30 and S31 and conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:42
S34		S33 and S16.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 10:43
S35	130747	(heat thermal) adj2 (stable stability)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:58

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S36	130	S13.ab. and S21.ab. and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:04
S37	11	S36 and S29 and S31 and conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:06
S38	10181	"fr-4" "fr 4" "fr4"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:06
S39	3752	S38 and S13 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:06
S40	6	S38 and S13 and S21 and (variable adj voltage)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:07
S41	25	S38 and S13 and S21 and (variable near2 voltage)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 11:16
S42	2232	(S38 with S16) and S21	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:17
S43	96897	S13 same (bisphenol cresol novolak novolac sma styrene styrenemaleic ppe polyphenylene polyphenyleneether)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:42
S44	498	S42 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:25
S45	79	S13 same (bisphenol) same (cresol novolak novolac) same (sma styrene styrenemaleic maleic) same (ppe phenylene polyphenylene polyphenyleneether)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR .	ON	2005/08/17 11:19
S46	6	S42 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:23

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S47	6	S38 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:23
S48	2	(variable near2 voltage) and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:24
S49	0	S13 and S21 and (variable near2 voltage) and S35 and conductive and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:26
\$50	. 0	S13 and S21 and (variable near2 voltage) and S35 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:26
S51	0	S13 and S21 and (variable near2 voltage) and S35 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:27
S52	624	S13 and S21 and S35 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 11:27
S53	0	S13 and S21 and S35 and S45	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:27
S54	832	S13 and S21 and S35 and conductive	US-PGPUB; USPAT; USOCR; EPO; IPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:27
S55	314	S13 and S21 and S35 and conductive and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:28
S56	7389	S13.ab. and S21.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON .	2005/08/17 11:29
S57	2	S56 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:30

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S58	1721	S56 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:30
S59	415746	(heat thermal) adj2 (stable stability resistance resistence resistiv\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:31
S60	523080	(heat thermal) near3 (stable stability resistance resistence resistiv\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:31
S61	902	S58 and S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:32
S62	193	S61 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:32
S63	. 133	S61 and S29 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 11:34
S64	45	S61 and S29 and S31 and (conductive conductiv\$)	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:42
S65	6	S61 and S29 and S31 and (conductive conductiv\$) and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:37
S66	2836	S38 with S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:42
S67	141	S66 with (bisphenol cresol novolak novolac sma styrene styrenemaleic ppe polyphenylene polyphenyleneether)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:43
S68	182	S66 same (bisphenol cresol novolak novolac sma styrene styrenemaleic ppe polyphenylene polyphenyleneether)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:44

S69	25763	halogenfree (free near2 halogen) "halogen-free" (non near5 (halogenated brominated chlorinated fluorinated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM TDB	OR	ON	2005/08/17 12:56
S70	1093	S13 with S69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:47
S71	288	S70 and S29 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 11:48
S72	168	S70 and S29 and S31 and S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 11:50
			; IBM_TDB			4
S73	63	S70 and S29 and S31 and S60 and conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB		ON	2005/08/17 11:50
S74		S70 and S29 and S31 and S60 and (conductive same (filler particle powder S31))	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	ON	2005/08/17 12:46
1			DERWENT			
S75	60	hsiao-ming.in. hsiao-ming-cheng.in. hsiao-ming-c.in. hsiao-ming-\$.in. hsiao-mingcheng.in. hsiao-mingcheng-\$.in.	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 12:47
S76	10	chien-tai.in. chien-tai-wen.in. chien-tai-w.in. chien-tai-\$.in. chien-taiwen. in. chien-taiwen-\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 12:48
			; IBM_TDB			100)
S77	25	wang-chang.in. wang-chang-yung.in. wang-chang-y.in. wang-changyung.in. wang-changyung-\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 12:49
S78	92	S75 S76 S77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:23
S79	4	S13 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 12:55

S80	287936	hardener curative (cross adj linker) crosslinker ((hardening curing (cross adj linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:59
S81	518364	epox\$5 polyepox\$5 diepox\$5 ((glycidyl diglycidyl polyglycidyl) adj ether) diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 12:56
S82	25763	halogenfree (free near2 halogen) "halogen-free" (non near5 (halogenated brominated chlorinated fluorinated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:17
S83	287411	(silica (silicon with (oxide dioxide)) (titanium with (oxide dioxide)) alumina ((aluminum magnesium) with hydroxide) (calcium with carbonate)) with (filler particle powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 13:57
S84	177100	conductive with (filler particle powder (aluminum with (nitride oxide)) (boron adj2 nitride) silver aluminum (zinc with oxide) nanotube (nano adj tube) "nano-tube")	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:13
S85	123	S80 and S81 and S82 and S83 and S84	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 13:14
S86	16	S85 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 13:01
S87	199867	(filler particle powder) with ((aluminum with (nitride oxide)) (boron adj2 nitride) silver aluminum (zinc with oxide) nanotube (nano adj tube) "nano-tube")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:39
S88	430	S80 and S81 and S82 and S83 and S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:39
S89	77	S80 and S81 and S82 and S83 and S87 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:14
S90	128568	(filler particle powder) with ((aluminum with (nitride oxide)) (boron adj2 nitride) silver (zinc with oxide) nanotube (nano adj tube) "nano-tube")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:57

S91	307	S80 and S81 and S82 and S83 and S90	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:50
S92	44	S80 and S81 and S82 and S83 and S90 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:49
S93	4859	(thermal thermally) with conductive with (filler powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:00
S94	47 i	S80 and S81 and S82 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:50
S95	22	S80 and S81 and S82 and S93 and S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:51
S96	22	S80 and S81 and S82 and S93 and S83	US-PGPUB;	OR	ON	2005/08/17 13:51
			USPAT; USOCR;	5.7		
			EPO; JPO; DERWENT		- *	
•	ji d		; IBM_TDB			part et et
S97	19	S80 and S81 and S82 and S93 and S83 and S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:55
S98	3	S96 not S97	US-PGPUB; USPAT; USOCR;	OR	ON	2005/08/17 13:55
	-		EPO; JPO; DERWENT	Y .		*
000	2661.42		; IBM_TDB		* *	Arada T
S99	766143	((aluminum with (nitride oxide)) (boron adj2 nitride) silver (zinc with oxide) nanotube (nano adj tube) "nano-tube")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:57
S100	1191079	(silica (silicon with (oxide dioxide)) (titanium with (oxide dioxide)) alumina ((aluminum magnesium) with hydroxide) (calcium with carbonate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:58
S101	46	S94 and S99 and S100	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 13:58

S102	301130	"pcb" "pwb" (printed adj2 (circuit wiring) adj2 board) (copper adj clad) "copper-clad" (foil adj clad) "foil-clad" (metal adj clad) "metal-clad"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON .	2005/08/17 15:29
S103	18131	S102 same S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:11
S104	3399	S103 and S80	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:11
S105	129	S104 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON -	2005/08/17 14:12
S106	106	S104 and S93 and S99 and S100	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:13
S107	70	S104 and S93 and S99 and S100 and (particle adj2 (size diameter))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:33
S108	508	S93 same (particle adj2 (size diameter))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:34
S109	234	S13 and S108	US-PGPUB; USPAT; USOCR;	OR	ON	2005/08/17 14:34
			EPO; JPO; DERWENT ; IBM_TDB	F		
S110	89	S13 and S108 and S102	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:34
S111	71.	S13 and S108 and S102 and S80	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 14:35
S112	518364	epox\$5 polyepox\$5 diepox\$5 ((glycidyl diglycidyl polyglycidyl) adj ether) diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:44

S113	130747	(heat thermal) adj2 (stable stability)	US-PGPUB;	OR	ON	2005/08/17 14:59
		(cost some) and (cost of the cost)	USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB			2003/03/17 1 1.03
S114	2166	S112 with S113	US-PGPUB;	OR	ON	2005/08/17 14:59
			USPAT; USOCR;			
			EPO; JPO;			
			DERWENT ; IBM_TDB			
S115	287936	hardener curative (cross adj linker) crosslinker ((hardening curing (cross adj linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT;	OR	ON	2005/08/17 16:45
		asj miking, crossinking, asj2 (agent promoter))	USOCR;			
			EPO; JPO; DERWENT			
S116	837	S114 and S115	; IBM_TDB US-PGPUB;	OR	ON	2005/08/17 14:59
3110	057		USPAT;	J OK	ON .	2003/08/17 14:39
		the state of the s	USOCR; EPO; JPO;	i.*	*	. 0
	•		DERWENT; IBM_TDB			
S117	4859	(thermal thermally) with conductive with (filler powder)	US-PGPUB;	OR	ON	2005/08/17 15:08
			USPAT; USOCR;			
			EPO; JPO; DERWENT			
21.0			; IBM_TDB			
S118	15	S116 and S117	US-PGPUB; USPAT;	OR .	ON	2005/08/17 15:08
			USOCR; EPO; JPO;		3 .	
			DERWENT ; IBM_TDB		÷	
S119	50372	conductive with (filler powder)	US-PGPUB;	OR	ON	2005/08/17 15:08
			USPAT; USOCR;			
			EPO; JPO; DERWENT			
	* .	S116 and S119	; IBM_TDB			
S120	36	S116 and S119	US-PGPUB; USPAT;	OR	ON	2005/08/17 15:08
			USOCR; EPO; JPO;			
			DERWENT ; IBM_TDB		€. 9	
S121	21	S120 not S118	US-PGPUB;	OR	ON	2005/08/17 15:14
			USPAT; USOCR;			
			EPO; JPO; DERWENT			
			; IBM_TDB			
S122	2	(S115 with S113) and S112 and S119	US-PGPUB; USPAT;	OR	ON	2005/08/17 15:16
		•	USOCR; EPO; JPO;			-8-
	.		DERWENT			
S123	5263	thermal near2 interface	; IBM_TDB US-PGPUB;	OR	ON	2005/08/17 15:16
		j	USPAT; USOCR;			111111111111111111111111111111111111111
			EPO; JPO;			
			DERWENT ; IBM_TDB			

		LASI Scaren History				
S124	58	S123 and S112 and S115 and S119	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ОИ	2005/08/17 15:16
S125	25763	halogenfree (free near2 halogen) "halogen-free" (non near5 (halogenated brominated chlorinated fluorinated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:04
S126	5	S124 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:21
S127	1093	S125 with S112	US-PGPUB; USPAT; USOCR; EPO; IPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:21
S128	8	S127 and S117	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:24
S129	60	hsiao-ming.in. hsiao-ming-cheng.in. hsiao-ming-c.in. hsiao-ming-\$.in. hsiao-mingcheng.in. hsiao-mingcheng-\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:23
S130	10	chien-tai.in. chien-tai-wen.in. chien-tai-w.in. chien-tai-\$.in. chien-taiwen. in. chien-taiwen-\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:23
S131	25	wang-chang.in. wang-chang-yung.in. wang-chang-y.in. wang-chang-y.in. wang-changyung.in. wang-changyung-\$.in.	US-PGPUB; USPAT; USOCR;	OR	ON	2005/08/17 15:23
	. •		EPO; JPO; DERWENT ; IBM_TDB			
S132	92	S129 S130 S131	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ОИ	2005/08/17 15:23
S133	23	S127 and S119	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:24
S134	301130	"pcb" "pwb" (printed adj2 (circuit wiring) adj2 board) (copper adj clad) "copper-clad" (foil adj clad) "foil-clad" (metal adj clad) "metal-clad"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:29

0100	1 (000		T		1	Talaanaa
S135	16383	(S112.ab. and S134) (S134.ab. and S112)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:30
S136	3947	S135 and S115	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:30
S137	285	S136 and S119	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:31
S138	107616	inorganic with (filler powder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 15:31
S139	86	S137 and S138	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ОИ	2005/08/17 15:53
S140	3	S137 and S138 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	ON	2005/08/17 15:33
5141			DERWENT ; IBM_TDB			
S141	9	S137 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ОИ	2005/08/17 15:33
S142	2	us-20050137293-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 15:57
S143	6153	(S112 same S113) (S112.ab. and S113.ab.)	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ОИ	2005/08/17 15:59
S144	527844	particle adj2 (size diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:05
S145	864	S143 and S144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:02

S146	766143	((aluminum with (nitride oxide)) (boron adj2 nitride) silver (zinc with oxide) nanotube (nano adj tube) "nano-tube")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:02
S147	1191079	(silica (silicon with (oxide dioxide)) (titanium with (oxide dioxide)) alumina ((aluminum magnesium) with hydroxide) (calcium with carbonate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR .	ON	2005/08/17 16:02
S148	304	S143 and S144 and S146 and S147	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:03
S149	186	S143 and S144 and S146 and S147 and S115	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:08
S150	353	(halogen near2 free) and (phosphorus near2 free)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 17:12
S151	118	S150 and S112	US-PGPUB; USPAT;	OR	ON	2005/08/17 16:36
			USOCR; EPO; JPO; DERWENT ; IBM_TDB			
S152	2	S150 and S117	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:36
S153	11257	(halogen near2 free)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 16:38
S154	409	S134 and S153 and S112	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:38
S155	34798	filler same (S144)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:38
S156	27	S154 and S155	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON .	2005/08/17 16:44

S157	81646	flame adj2 (proof retardant retardent retard\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:44
S158	518364	epox\$5 polyepox\$5 diepox\$5 ((glycidyl diglycidyl polyglycidyl) adj ether) diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:44
S159	287936	hardener curative (cross adj linker) crosslinker ((hardening curing (cross adj linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:45
S160	99002	(inorganic conductive) adj2 (filler powder additive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:46
S161	120125	(inorganic conductive) near3 (filler powder additive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:46
\$162	2908	S157 and S158 and S159 and S161	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/08/17 16:47
S163	402	S157 and S158 and S159 and S161 and S113	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:48
S164	57	S157 and S158 and S159 and S161 and S113 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:49
S165	315	S157 and S158 and S159 and S161 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:48
S166	7924	S125.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:50
S167	105	S162 and S166	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 16:50

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S168	355	(halogen near2 (free devoid)) and (phosphorus near2 (free devoid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 17:12
S169	119	S112 and S168	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 17:13
S170	25	S112 and S168 and S161	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/17 17:13
S171	6946	523/400.ccls. 523/440.ccls. 523/442.ccls. 523/443.ccls. 523/445.ccls. 523/457.ccls. 523/458.ccls. 523/459.ccls. 523/466.ccls. 523/468.ccls. 525/523.ccls. 525/529.ccls. 525/530.ccls. 525/533.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:01
S172	766725	((aluminum with (nitride oxide)) (boron adj2 nitride) silver (zinc with oxide) nanotube (nano adj tube) "nano-tube")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:02
S173	1192009	(silica (silicon with (oxide dioxide)) (titanium with (oxide dioxide)) alumina ((aluminum magnesium) with hydroxide) (calcium with carbonate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:02
S174	518772	epox\$5 polyepox\$5 diepox\$5 ((glycidyl diglycidyl polyglycidyl) adj ether) diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:02
S175	288138	hardener curative (cross adj linker) crosslinker ((hardening curing (cross adj linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT;	OR	ON	2005/08/18 11:02
	ě.		USOCR; EPO; JPO; DERWENT			=======================================
S176	23858	S174 and S175 and S172 and S173	; IBM_TDB US-PGPUB;	OR	ON	2005/08/18 11:02
		3.73 2.73 2.73 2.73	USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB		OI4	2005/06/16 11.02
S177	1000	S171 and S176	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:03
S178	25781	halogenfree (free near2 halogen) "halogen-free" (non near5 (halogenated brominated chlorinated fluorinated))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:04

6170	47	0127 4 0170	Tue nenum.	I OD	l ou	2005/00/18 11 04
S179	47	S177 and S178	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:04
S180	528180	particle adj2 (size diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:05
S181	19	S179 and S180	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/08/18 11:05
S182	0	jp-43006302-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:39
S183	0	jp-430006302-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:29
S184	0	jp-4306302-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/03/23 15:31
S185	0	suzuki-munehiko-\$.in.	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:31
S186	60894	showa.as.	US-PGPUB; USPAT; USOCR;	OR	ON	2006/03/23 15:35
			EPO; JPO; DERWENT ; IBM_TDB		(1)	
S187	219	kawamata-takeshi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:33
S188	8	suzuki-munehiko.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:34
S189	223	hosokawa-etsuo.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:33

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S190	0	S187 and S188 and S189	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:33
S191	0	suzuki-munehiko.in.	JPO	OR	ON	2006/03/23 15:34
S192	28097	showa.as.	JPO	OR	ON	2006/03/23 15:35
S193	199	S192 and (S187 S189 S188)	JPO	OR	ON	2006/03/23 15:38
S194	0	(isoindolinecarboxylic (isoindoline adj2 carboxylic)) with (aminophenyltolyl (aminophenyl adj2 tolyl))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:40
S195		(indolinecarboxylic (indoline adj2 carboxylic)) with (aminophenyltolyl (aminophenyl adj2 tolyl))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:42
S196	0	carboxylic with (aminophenyltolyl (aminophenyl adj2 tolyl))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/23 15:42
S197	25114	trimellitic benzenetricarboxylic isobenzofurancarboxylic phthalancarboxylic carboxyphthalic anhydrotrimellitic trimellic (benzene adj2 tricarboxylic) (isobenzofuran adj2 carboxylic) (phthalan adj2 carboxylic) (carboxy adj2 phthalic) (anhydro adj2 trimellitic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:24
S198	19661	methylenebisbenzeneamine (methylenebis adj2 benzeneamine) (methylenebis adj2 benzene adj2 amine) (methylene adj2 bisbenzeneamine) (methylene adj2 bisbenzeneamine) (methylene adj2 bisbenzeneamine) (methylene adj2 bis adj2 benzeneadj2 amine) aminobenzylaniline (amino adj2 benzylaniline) (aminobenzyladj2 amiline) (amino adj2 benzyl adj2 aniline) (diamino adj2 diphenylmethane) (diaminodiphenylmethane) (diamino adj2 diphenylmethane) (diaminodiphenyl adj2 methane) (diamino adj2 diphenyl adj2 methane) diaminoditan (diamino adj2 diamine) (diphenylmethane adj2 diamine) (diphenyl adj2 methane adj2 diamine) (methylene adj2 diamiline) aminophenylmethane (amino adj2 phenylmethane) (aminophenyl adj2 methane) (amino adj2 phenyl adj2 methane) (amino adj2 phenylmethane) (aminomethane (dianilino adj2 methane) curithane methylenebisaniline (methylenebis adj2 aniline) (methylene adj2 bisaniline) (methylene adj2 bis adj2 aniline)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:33
S199	850	S197 with S198	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:33
S200	386	S197 with S198 with (adduct react reaction reacting reacted)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:36
S201	569154	epox\$6 diepox\$6 polyepox\$6 glycidyl\$ diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:35

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S202	183	S200 and S201	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:35
S203	459	S199 and S201	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR .	ON	2006/03/24 08:35
S204	299098	hardener curative (cross adj2 linker) crosslinker ((hardening curing (cross adj2 linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:37
S205	212	S199 same S204	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:37
S206	5	S199 same (retardant retarding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:38
S207	214	S205 S206	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:37
S208	208	S207 and S201	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR .	ON	2006/03/24 08:38
S209	55	S200 same (S204 retardant retard retarding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/03/24 08:39
S210	51	S209 and S201	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:51
S211	714137	amide polyamide imide polyimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:52
S212	2962	S211 and S197 and S198	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:52

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S213	30942	(S211 S199) same (S204 retard retarding retardant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:53
S214	734	S212 and S213	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:53
S215	2042	S201 and S212	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:53
S216	671	S201 and S212 and S213	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR **	ON	2006/03/24 08:54
S217	1349	S201 and S212 and S204	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:55
S218	. 254	S217 and S199	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/03/24 08:55
S219	52846	conductive with (powder filler)	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:55
S220	15	S218 and S219	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 08:56
S221	85	S217 and S219	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:03
S222	135	trimellitimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:04
S223	29	S222 and S201	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:04

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S224	10	S222 and S201 and S204	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:10
S225	1	1981-24862D.NRAN.	DERWENT	OR	OFF	2006/03/24 09:08
S226	2814	S201 and S211 and S204 and S219	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:11
S227	107350	(filler powder) with ((titanium aluminum magnesium calcium) near3 (oxide dioxide hydroxide carbonate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:13
S228	1145	S226 and S227	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:13
S229	549250	particle adj2 (size diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:13
S230	13203	S227 same S229	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:13
S231	301	S226 and S230	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR -	ON	2006/03/24 09:15
S232	131374	(filler powder) with ((aluminum adj2 nitride) (boron adj2 nitride) silver aluminum (zinc adj2 oxide) nanotube (nano adj2 tube))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:15
S233	17201	S229 same S232	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR .	ON	2006/03/24 09:15
S234	221	S226 and S230 and S233	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:16
S235	1655031	semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:16

		27151 Scarch History				
S236	79	S234 and S235	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:17
S237	298	S201.ab. and semiconductor.ab. and S219.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:19
S238	42	S201.ab. and semiconductor.ab. and S219.ab. and S211.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:19
S239	25	S201.ab. and semiconductor.ab. and S219.ab. and inorganic.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/24 09:19
S240	569240	epox\$6 diepox\$6 polyepox\$6 glycidyl\$ diglycidyl\$ polyglycidyl\$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:19
S241	52860	conductive with (powder filler)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	ÓR	ON	2006/03/27 14:59
S242	312	S240.ab. and (semiconductor encapsulant encapsulat\$5 underfil underfill). ab. and S241.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:44
S243	1174609	silica ((silicon aluminum) adj2 (oxide dioxide trioxide)) (titanium adj2 (oxide dioxide)) alumina ((aluminum magnesium) adj2 hydroxide) (calcium adj2 carbonate)	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	ON	2006/03/27 14:31
2			DERWENT; IBM_TDB	3	1	
S244	1739505	(aluminum adj2 (nitride oxide)) (boron adj2 nitride) silver aluminum (zinc adj2 oxide) nanotube (nano adj tube) "nano-tube"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:32
S245		S242 and S243 and S244	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:34
S246	299178	hardener curative (cross adj2 linker) crosslinker ((hardening curing (cross adj2 linking) crosslinking) adj2 (agent promoter))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:45

S247	60	S240 with (semiconductor encapsulant encapsulat\$5 underfil underfill).ab.	US-PGPUB:	OR	ON	2006/03/27 14:47
3247	00	and S241 and S246	USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OK .	ON	2000/03/27 14.47
S248	10	S240 with (semiconductor encapsulant encapsulat\$5 underfil underfill).ab. and S241 and (S246 with (thermal thermally))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:48
S249	95	(S240 with (semiconductor encapsulant encapsulat\$5 underfil underfil!)) and S241 and (S246 with (thermal thermally))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:50
S250	18	(S240 with (semiconductor encapsulant encapsulat\$5 underfil underfill)) and S241 ab. and (S246 with (thermal thermally))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 15:00
S251	285680	(conductive metal metallic) with (powder filler)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 14:59
S252	23	(S240 with (semiconductor encapsulant encapsulat\$5 underfil underfill)) and S251.ab. and (S246 with (thermal thermally))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/03/27 15:03
S253	107	(S240 with (semiconductor encapsulant encapsulat\$5 underfil underfill)) and S251 and (S246 with (thermal thermally)) and S243 and S244	; IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/03/27 15:05
S254	. 8	(S240 with (semiconductor encapsulant encapsulat\$5 underfil underfill)) and S251 and (S246 with (thermal thermally heat) with (stabiliz\$6 stabilit\$5)) and S243 and S244	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/03/27 15:07
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